L Number			DB	Time stamp
2	Hits	Search Text	USPAT	2002/08/05 12:50
	1979	438/108.ccls. or 438/118.ccls. or	UJIKI	2002,00,03 12.00
		438/119.ccls. or 438/124.ccls. or		
		438/126.ccls. or 438/127.ccls.	USPAT	2002/08/05 12:51
1	722 ,	438/106.ccls.	USPAT	2002/08/05 13:58
4	291	438/106.ccls. and (438/108.ccls. or	UJIMI	2002/00/03 13:30
, ,	Į	438/118.ccls. or 438/119.ccls. or		
. !		438/124.ccls. or 438/126.ccls. or		1
i .	_	438/127.ccls.)	HCDAM.	2002/08/05 13:58
5	2410	438/106.ccls. or (438/108.ccls. or	USPAT	2002/08/03 13.30
1		438/118.ccls. or 438/119.ccls. or		
		438/124.ccls. or 438/126.ccls. or		
		438/127.ccls.)		2002/08/05 14:00
6	470	(438/106.ccls. or (438/108.ccls. or	USPAT	2002/08/05 14:00
		438/118.ccls. or 438/119.ccls. or	7	
		438/124.ccls. or 438/126.ccls. or		
		438/127.ccls.)) and ((encapsul\$5 or resin	1 67	:
		or paste or goop or adhesive or polymer)		1
		with (pool or reservoir or cup or well))		1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
7	152	((438/106.ccls. or (438/108.ccls. or	USPAT	2002/08/05 14:00
		438/118.ccls. or 438/119.ccls. or		1
1		438/124.ccls. or 438/126.ccls. or		ļ
!) 	438/127.ccls.)) and ((encapsul\$5 or resin		i
:	1	or paste or goop or adhesive or polymer)		
1		with (pool or reservoir or cup or well)))		1
'	!	and (flip adj chip)		
i 8 .	97382	((encapsul\$5 or resin or paste or goop or	USPAT	2002/08/05 14:01
i	:	adhesive or polymer) with (pool or		
!	!	reservoir or cup or well))		
9	763	(((encapsul\$5 or resin or paste or goop or	USPAT	2002/08/05 14:01
'	,03	adhesive or polymer) with (pool or	ĺ	
!		reservoir or cup or well))) and		
		((flip-chip) or (flip adj chip))		
10	124931	((encapsul\$5 or resin or paste or goop or	USPAT;	2002/08/05 14:01
10	124931	adhesive or polymer) with (pool or	EPO; JPO;	
		reservoir or cup or well))	DERWENT;	
		reservoir or cup or weir,	IBM TDB	1
10	705	(((encapsul\$5 or resin or paste or goop or	USPAT;	2002/08/05 14:03
12	785	adhesive or polymer) with (pool or	EPO; JPO;	2002,007
		reservoir or cup or well))) and ((flip adj	DERWENT;	
		reservoir or cup or well)) and ((life ad)	IBM TDB	
	4.57	chip) or (flip-chip))	USPAT;	2002/08/05 14:33
13	137	(((encapsul\$5 or resin or paste or goop or	EPO; JPO;	2002/00/03 11:33
		adhesive or polymer) with (pool or	DERWENT;	
		reservoir or cup or well))) and (resin adj	IBM TDB	
1		pool)	USPAT	2002/08/05 15:25
3	1688	(438/108.ccls. or 438/118.ccls. or	USPAI	2002/00/03 13.23
t		438/119.ccls. or 438/124.ccls. or	1	
i		438/126.ccls. or 438/127.ccls.) not		
		438/106.ccls.	HCDAM	2002/08/05 15:38
15	459	((438/108.ccls. or 438/118.ccls. or	USPAT	2002/06/03 13:38
	1	438/119.ccls. or 438/124.ccls. or		
i	1	438/126.ccls. or 438/127.ccls.) not		
	1	438/106.ccls.) and (flip adj chip)		2002/00/05 15:30
16	0	1 1	USPAT	2002/08/05 15:39
	1	dipping or dips)		1 0000 100 105 15 50
	0		USPAT	2002/08/05 15:39
17	34		USPAT	2002/08/05 15:39
17 18	,	dipping or dips)		
		dipping of dipo/		
	9		USPAT	2002/08/04 17:49
		flip adj chip adj bonding adj apparatus	USPAT	2002/08/04 17:49
	9 224	flip adj chip adj bonding adj apparatus berezny.xa. berezny.xa. and nema		2002/08/04 17:49 2002/08/04 17:50
	9	flip adj chip adj bonding adj apparatus berezny.xa. berezny.xa. and nema	USPAT	2002/08/04 17:49 2002/08/04 17:50 2002/08/04 17:51
	9 224 126	flip adj chip adj bonding adj apparatus berezny.xa. berezny.xa. and nema (berezny.xa. and nema) and flip	USPAT USPAT	2002/08/04 17:49 2002/08/04 17:50 2002/08/04 17:51 2002/08/04 17:51
	9 224 126 25	flip adj chip adj bonding adj apparatus berezny.xa. berezny.xa. and nema (berezny.xa. and nema) and flip murakami.in. murakami.in. and NEC	USPAT USPAT USPAT USPAT USPAT	2002/08/04 17:49 2002/08/04 17:50 2002/08/04 17:51 2002/08/04 17:51 2002/08/04 18:02
	9 224 126 25 3963 63	flip adj chip adj bonding adj apparatus berezny.xa. berezny.xa. and nema (berezny.xa. and nema) and flip murakami.in. murakami.in. and NEC	USPAT USPAT USPAT USPAT USPAT	2002/08/04 17:49 2002/08/04 17:50 2002/08/04 17:51 2002/08/04 17:51
	9 224 126 25 3963	flip adj chip adj bonding adj apparatus berezny.xa. berezny.xa. and nema (berezny.xa. and nema) and flip murakami.in. murakami.in. and NEC ((flip adj chip) or (flip-chip)) and (pool	USPAT USPAT USPAT USPAT USPAT	2002/08/04 17:49 2002/08/04 17:50 2002/08/04 17:51 2002/08/04 17:51 2002/08/04 18:02
	9 224 126 25 3963 63	flip adj chip adj bonding adj apparatus berezny.xa. berezny.xa. and nema (berezny.xa. and nema) and flip murakami.in. murakami.in. and NEC ((flip adj chip) or (flip-chip)) and (pool or pools reservoir or reservoir or (resin	USPAT USPAT USPAT USPAT USPAT	2002/08/04 17:49 2002/08/04 17:50 2002/08/04 17:51 2002/08/04 17:51 2002/08/04 18:02
	9 224 126 25 3963 63 243	flip adj chip adj bonding adj apparatus berezny.xa. berezny.xa. and nema (berezny.xa. and nema) and flip murakami.in. murakami.in. and NEC ((flip adj chip) or (flip-chip)) and (pool or pools reservoir or reservoir or (resin adj pool))	USPAT USPAT USPAT USPAT USPAT	2002/08/04 17:49 2002/08/04 17:50 2002/08/04 17:51 2002/08/04 17:51 2002/08/04 18:02
	9 224 126 25 3963 63 243	flip adj chip adj bonding adj apparatus berezny.xa. berezny.xa. and nema (berezny.xa. and nema) and flip murakami.in. murakami.in. and NEC ((flip adj chip) or (flip-chip)) and (pool or pools reservoir or reservoir or (resin	USPAT USPAT USPAT USPAT USPAT USPAT	2002/08/04 17:49 2002/08/04 17:50 2002/08/04 17:51 2002/08/04 17:51 2002/08/04 18:02 2002/08/04 18:07

-	180	((flip adj chip) or (flip-chip)) and	USPAT	2002/08/05 12:49
		(reservoir or reservoir or (resin adj		
		pool))		